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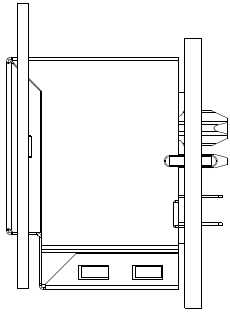
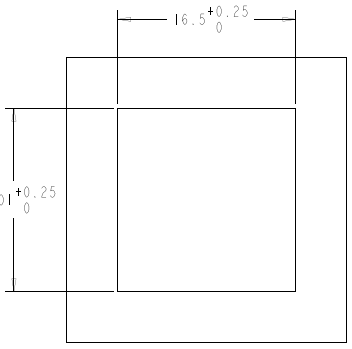
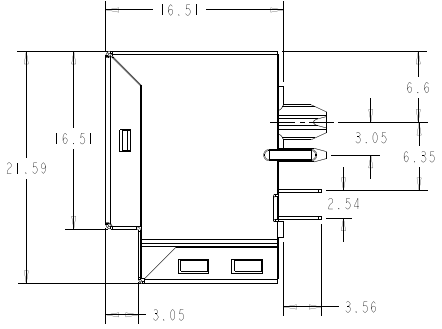
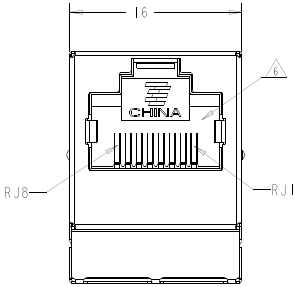
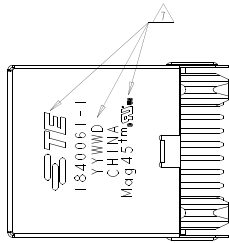
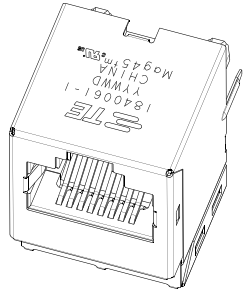
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LOC		REV		REVISIONS			
AA	00	REV	DATE	DESCRIPTION	INIT	APP	APPD
		A		INITIAL RELEASE			



MATERIALS
 HOUSING: THERMOPLASTIC, BLACK, FLAMMABILITY RATED UL 94V-0
 SHIELD: BRASS, 0.20mm THICK
 PREPLATED WITH MIN 0.76um SEMI-BRIGHT NICKEL
 POST DIPPED WITH 2.54um MIN SAC SOLDER AT GROUND PINS.
 CONTACT: PHOSPHOR BRONZE
 WITH 1.27um MIN OVERALL NICKEL UNDERPLATE AND
 SELECTIVE 1.27um MIN GOLD PLATING AT MATING INTERFACE
 SOLDER TAIL: PHOSPHOR BRONZE
 WITH 1.27um MIN OVERALL NICKEL UNDERPLATE AND
 PLATED WITH 2.54um MIN TIN

MAGNETICS
 -APPLICATION: 10/100 BASE-T, EXTENDED TEMPERATURE
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CRIMP-CABLE): TX = 1:1, RX = 1:1
 -OPEN CIRCUIT INDUCTANCE (OCL): 350nH MIN @100MHz, 0.1uVRMS,
 5mADC BIAS FROM -40°C TO +85°C, TX AND RX
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A
 RISE TIME OF 500V/SEC

- 4. OPERATING TEMPERATURE: FROM -40°C TO +85°C
- ALL DIMENSIONS TO BE NOMINAL UNLESS OTHERWISE NOTED
- RJ45 CAVITY CONFORMS TO FCC RULES AND REGULATION PART 68 SUB-PART F.
- TRADEMARK, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN, AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOW
- 8. THIS PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK SOLDERING TEMPERATURE IS 260 °C MAX., 10 SECONDS MAX

1840061-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV: PAUL PENG	DATE: 05/20/2011	TE Connectivity	
DESIGNER: JIM		APP: MARTIN LIU	DATE: 05/20/2011		
CHECKER: JIM		APP: JIM BAO	DATE: 05/20/2011	IXL MAG45(TM) MODULAR JACK, VERTICAL TYPE, 426ETP13 CIRCUIT, WITHOUT LED	
DRAWN: JIM		APP: JIM BAO	DATE: 05/20/2011	SCALE: 1:1	SHEET: 1 OF 2
APPROVAL: JIM		DATE: 05/20/2011	REV: 00	DRAWING NO: 1840061	ISSUED TO: -
CUSTOMER DRAWING		SCALE: 3:1	SHEET: 1 OF 2	REV: A	

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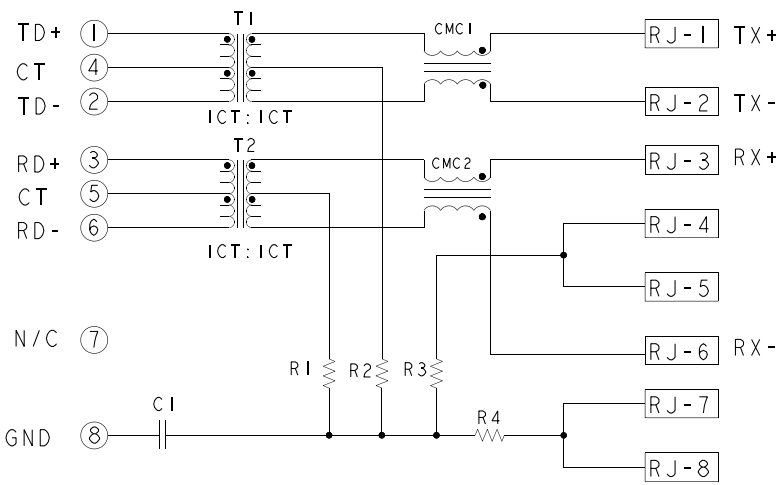
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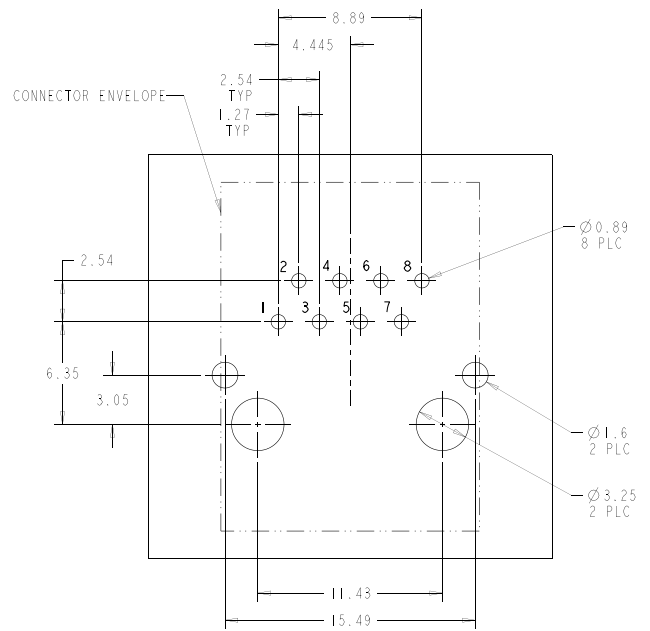
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LOC		REV		REVISIONS		DATE	BY	APPD
AA	00							
				SEE SHEET 1				

426ETPI3 10/100 BASE-T CIRCUIT



C1 = 1000pF, 2KV, CAPACITOR
 R1 - R4 = 75 ohms, RESISTOR



SUGGESTED PCB LAYOUT (TOL: ±0.05)
 (COMPONENT SIDE VIEW)

THIS DRAWING IS A CONTROLLED DOCUMENT.		AW: PAUL PENG	OSMATZ011	TE Connectivity	
DESIGNER: JIM	DATE: 01/11/00	AW: PAUL PENG	OSMATZ011	IXI MAG45(TM) MODULAR JACK, VERTICAL TYPE, 426ETPI3 CIRCUIT, WITHOUT LED	
DATE: 01/11/00	APPD: JIM	AW: PAUL PENG	OSMATZ011	SCALE: 1:1	DRAWING NO: 1840061
REV: 1	REV: 1	REV: 1	REV: 1	SHEET: 2	OF: 2
CUSTOMER DRAWING				DATE: 3-1-00	REV: A